

Specifications

Mechanics

<i>X, Y table</i>	Working area 100 x 100 mm Resolution 0.25 µm, repeatability < 2 µm
<i>Z-axis</i>	60 mm
<i>Speed</i>	All axes programmable from 0,2...16 mm/s ≤ 30 wires / min.
<i>Bond head</i>	Wedge-Wedge Thin-Wire (Au/Al) or Ribbon Axis of rotation ± 360°

Ultrasonic system

60KHz / 100kHz optional 140KHz

Wire size

17,5mm up to 75µm

Ribbon size

30 µm x 12,5 µm – 250 µm x 25 µm

Control

Heating-controller

Integrated in machine 0 - 250 °C optional

Computer

Single-Board PC, 1,6 GHz Pentium processor,
1 GB RAM, ethernet, USB 4x + 4x frontside

Monitor

TFT flat screen

Operation system

Windows XP

Printer

All Windows-compatible printers can be installed
All bonding parameters can be printed

Work holder

ø 80mm or optional 4"x4"

Heated work holder

ø 80mm and optional 4"x4"
(mech. / vacuum) (Attention: 4x4" up to 200°C)

5632DA

Semi-automatic Wedge-Wedge-Bonder

The semi-automatic Wedge-Wedge Bonder 5632 fills the gap between the manual Wedge-Bonders series 53xx and 54xx from F&K Delvotec Semiconductor to the automatic-Bonder from F&K Delvotec.

The 5632 Deep-Access Bonder can be used also as Ribbon-Bonder.

He is on basis 5600-series fully PC controlled and allows any number of bonds to be programmed.

Pre-programmed adjust points are targeted through the camera's cross hair targeting system and the programmed bonds are executed automatically.

Two operating modes are available: Single bond for repair of various bond samples and making single bonds (manual-automatic) and multi wire for teaching and bonding chips or various bond samples (semi and fully automatic).

The 5632 can also be used as Gold Wire, Ball or Alu Heavy Wire Bonder as well as pull-/shear tester by simply replacing the bond head and loading the appropriate software.

change over time: approx. 5 minutes.
Ask us for more information !



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Other features

Programming:

Automatic bonding of hybrids or COB
with programmable X/Y table

Work holders



For components up to 4 x 4"
Vacuum and mechanical clamping

Heated workholders optional



For components up to 4 x 4"
Vacuum and mechanical clamping
Heated



For components up to \varnothing 80 mm
Vacuum and mechanical clamping
heated

More Work holders available on request.

Head Parking System

For storing of temporary not required bondhead
(5610 / 5630 / 5632 / 5650)
or pull- and shear-heads.
Can be mounted on the left or right side of the machine

General

Camera

With cross hair targeting for positioning of bonds / chips

Microscope

Motic (Stereoscope Leica S6, other microscopes optional)

Lighting

20 W halogen spot light, optional LED direct light
Incident light optional

Dimensions

Height 70 cm, width 70 cm, depth 65 cm; approx. 70 kg

Supplies

100...240 VAC, single-phase, 50/60 Hz, max. 500 VA

Connections

Air 6 bar, vacuum 0,7 bar \varnothing 6 mm

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